

IEEE SW Test Workshop

Semiconductor Wafer Test Workshop

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Reinforcement of PCB using Advanced Stiffeners for High Pin Count Devices



June 3-6, 2007

San Diego, CA USA

Overview

- Why Reinforce the PCB?
- Objective : Fight the Deflection!
- Customer Case Study
- Calculation using Analytical Techniques
- Analysis with FEA Simulation
- Reduce the Deflection with Advanced Stiffener & Pogo Modules Optimization
- Summary/Conclusion

Why Reinforce the PCB ?

- With Devices getting More Complex :
 - Need of increased Pin Count per Probe Head
 - Growing Need of Tester Channel Resources with more Pogo Module & Population
- By Definition the PCB is Subjected to Probe Force and Pogo Tower Load
- Risk : PCB Deflection Creates Probe Contact Issue with Wafer (Yield Drop, Opens...) & fatigue failure during lifetime.

Fight the Deflection!

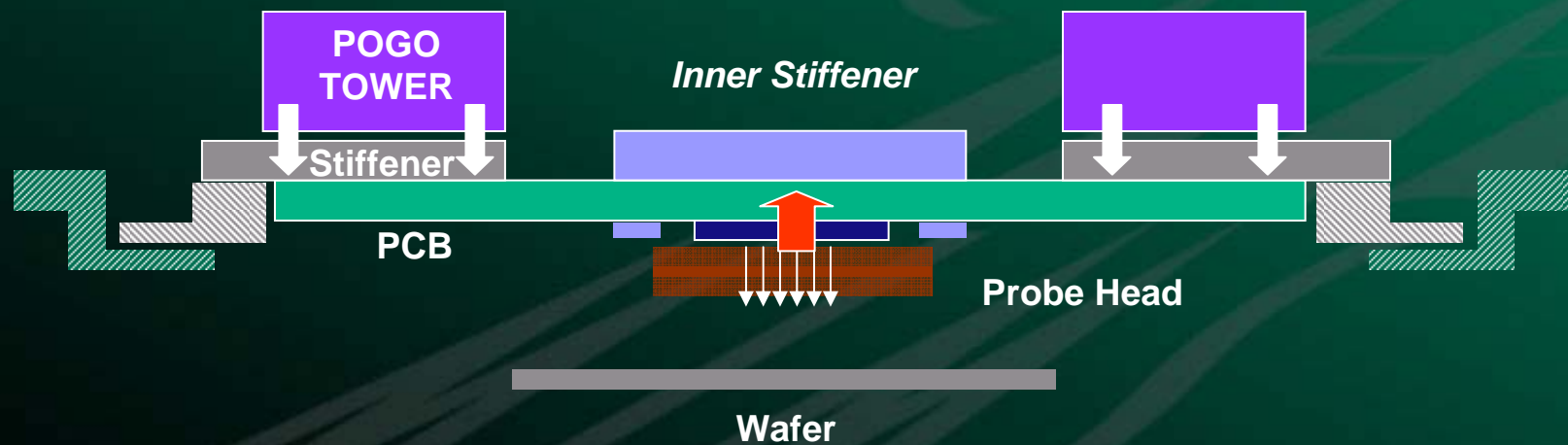
Questions to resolve:

1. Is my standard stiffener (or added stiffener) good enough to reduce deflection generated from Pogo load & Probe force?
 2. Where are the most critical deflection areas located on my PCB?
 3. Can I quantify the maximum deflection value?
 4. How do I define the best Advanced Stiffener parameters (thickness, spokes number, width...)?
- Let's go through a Customer Case Study

Customer Case Study

Issue:

“Probe Head planarity issue on the wafer: about 100 μ m (4mils) OD to get the full contact”. Standard planarity should be 2 mils (50 μ m).

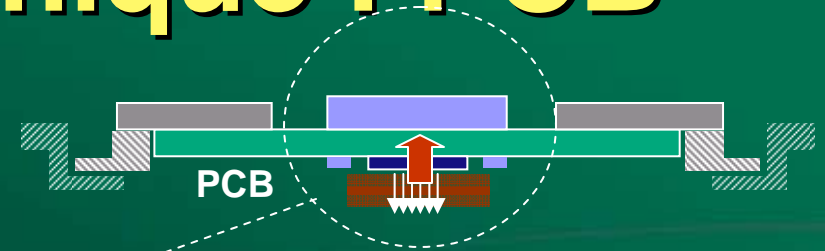
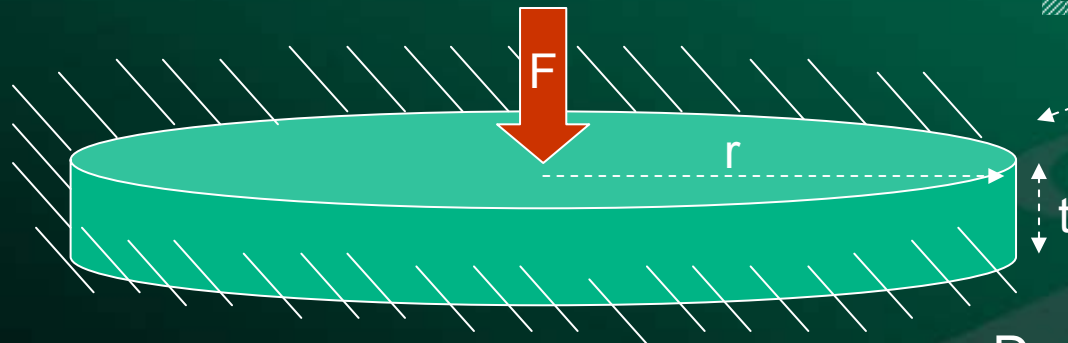


Test Description :

8300 Probes, 3 mils, Flat Tip, Room Temp, Prober Reliable.
PCB Thickness 4.75mm, Outer Diameter 280mm, Inner Diameter 180mm.
Stiffener Thickness 12.7mm

Analytical Technique : PCB

Based on Kirchhoff Theory



$$D_{\max} = -\frac{(10 \times F) \times r^2 \times 12(1 - \sigma^2)}{16\pi \times E \times t^3}$$

$$D_{\max} = f\left(\frac{F \times r^2}{t^3}\right)$$

D_{\max} : PCB Max Deflection (mm)

F : Total Probe Force (Kg)

r : PCB Inner Radius (mm)

t : PCB Thickness (mm)

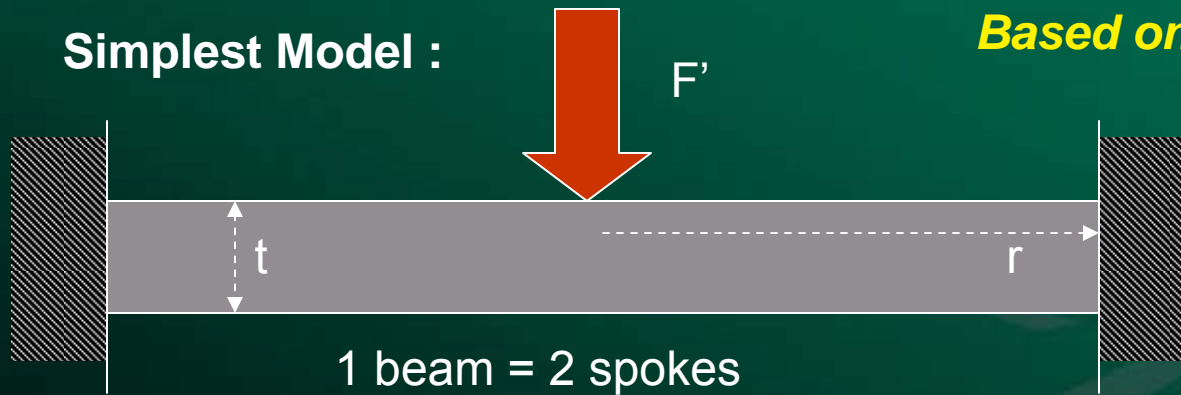
σ : PCB Poisson's Ratio

E : PCB Young's Modulus (MPa)

PCB $D_{\max} = 556\mu\text{m}$

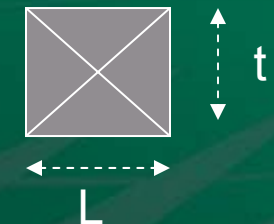
Analytical Technique : Stiffener

Simplest Model :



Based on Beam Theory

Spoke Section



$$D_{max} = -\frac{(10 \times F') \times (2.r)^3 \times 12}{192 \times E \times L \times t^3}$$

With $F' = F/(n/2)$

$$D_{max} = f\left(\frac{F \times r^3}{n \times L \times t^3}\right)$$

D_{max} : Spoke Deflection Max (mm)

F : Total Probe Force (Kg)

F' : Force on One Beam (Kg)

r : Spoke Length (mm)

t : Spoke Thickness (mm)

L : Spoke Width (mm)

n : Number of Spokes

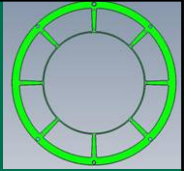
E : Spoke Young's Modulus (MPa)

Stiffener $D_{max} = 90\mu\text{m}$ (with $n = 4$ and $L = 6\text{mm}$)

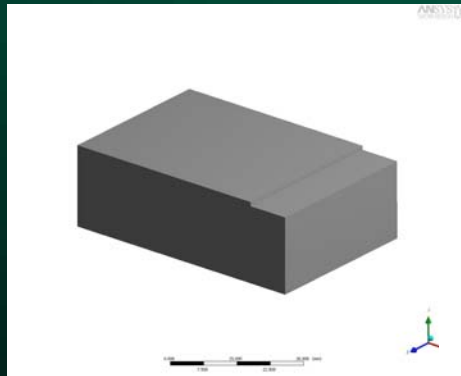
Observation

Analytical Technique Gives an idea of the Deflection of the Individual Entities such as the PCB or Stiffener Spokes, however :

- It is a “2D Analysis” Estimating the Max Deflection
- Not Possible to do Complex Assembly Stack-up Studies
- Not Possible to Evaluate Multiple Load Cases



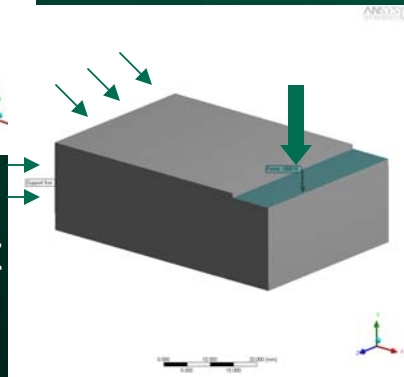
FEA Reminder



3D
Modeling

Force Load,
Boundary
Condition &
Material Properties

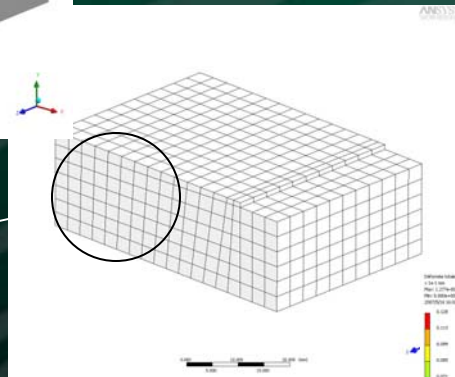
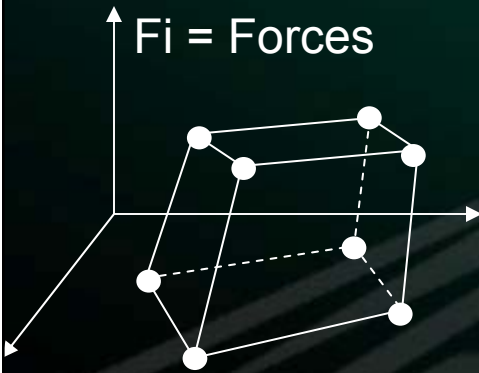
COSMOS
&
ANSYS
Workbench



Meshing
Procedure

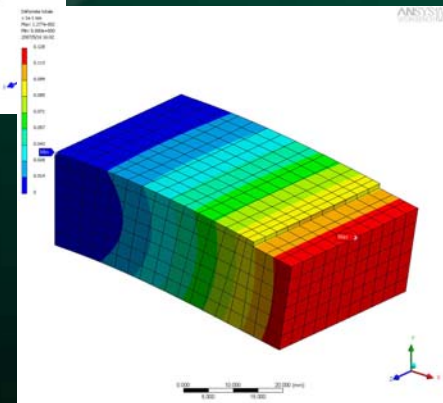
U_i = Displacement

F_i = Forces

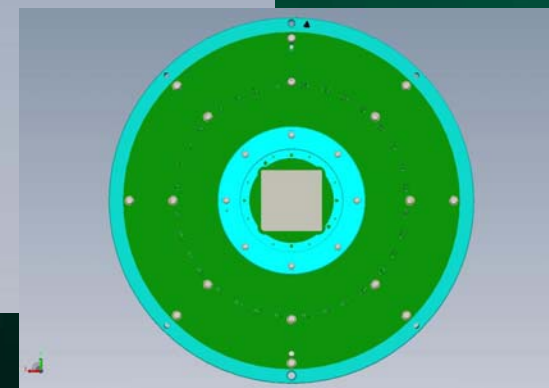
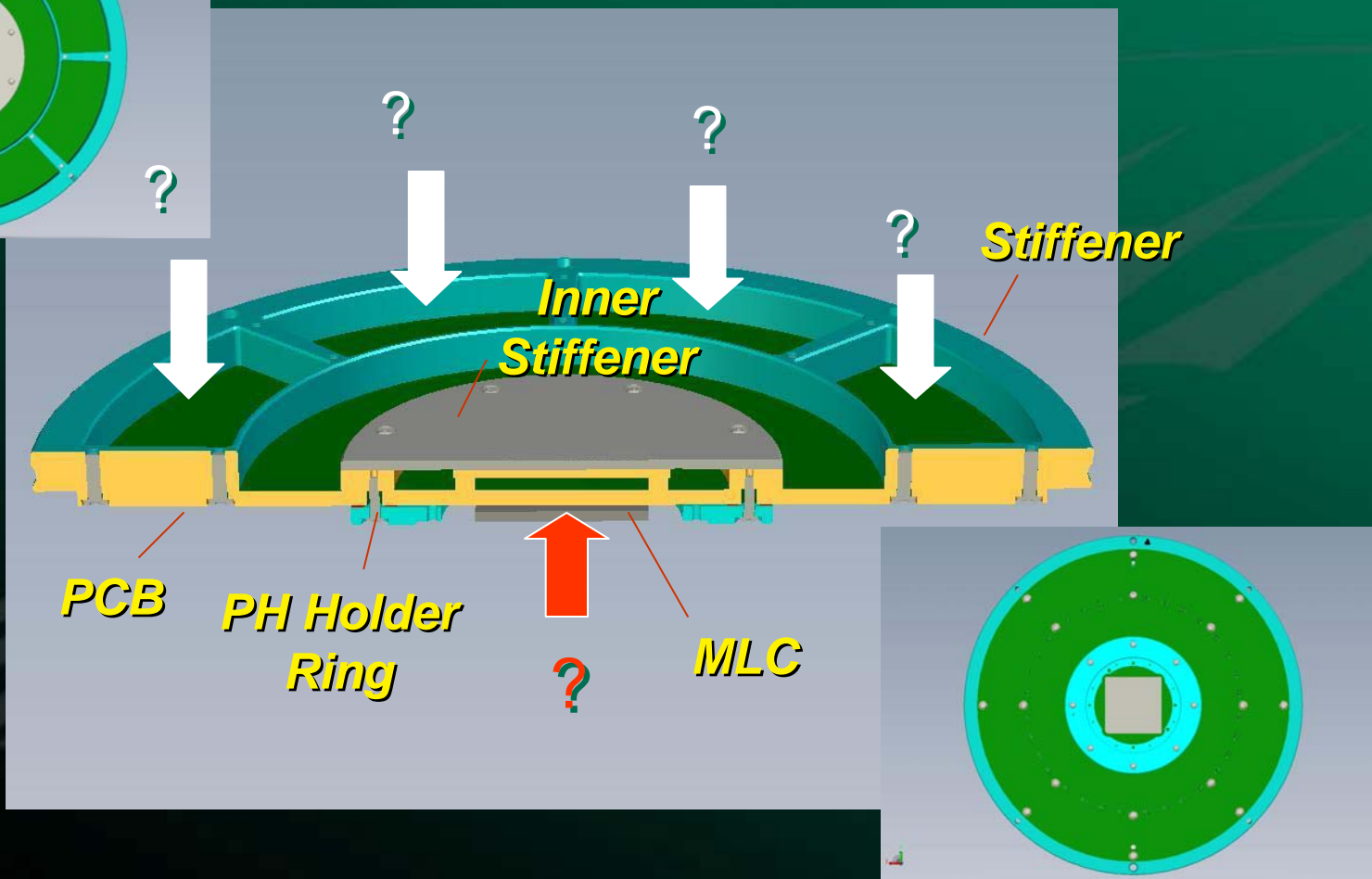
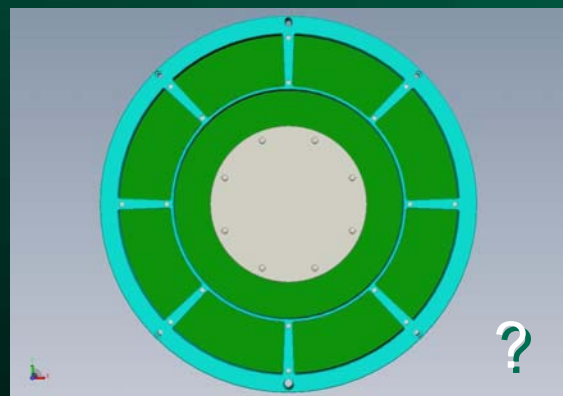
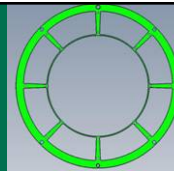


Computation &
Visualization

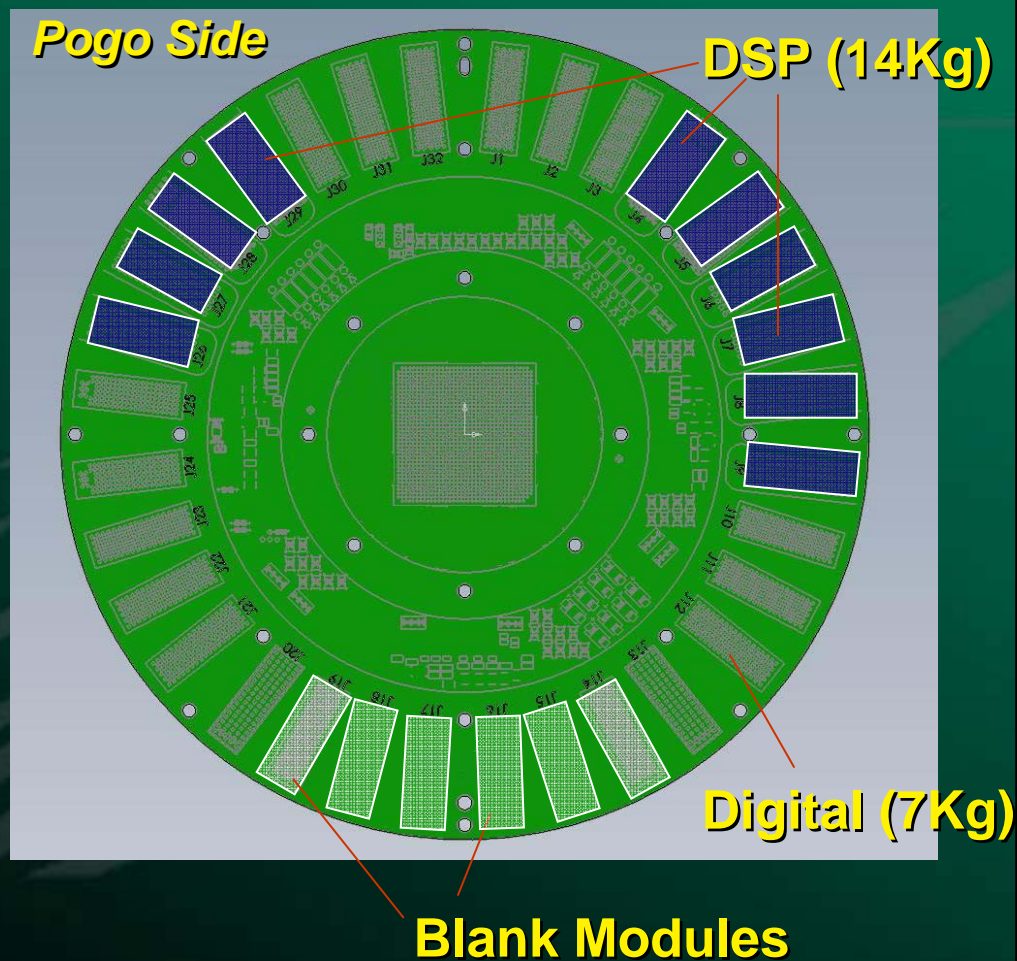
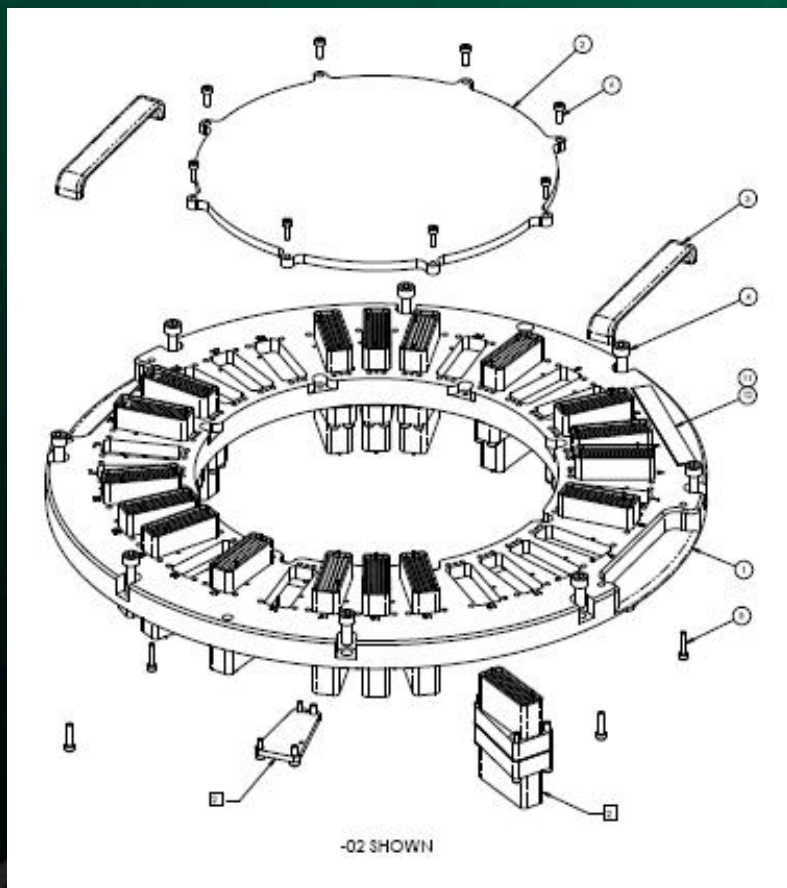
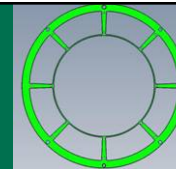
Break the Model up into Small
Element with Nodes



3D Space Modeling

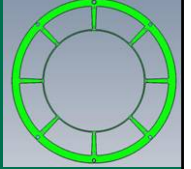


Pogo Module Load on PCB



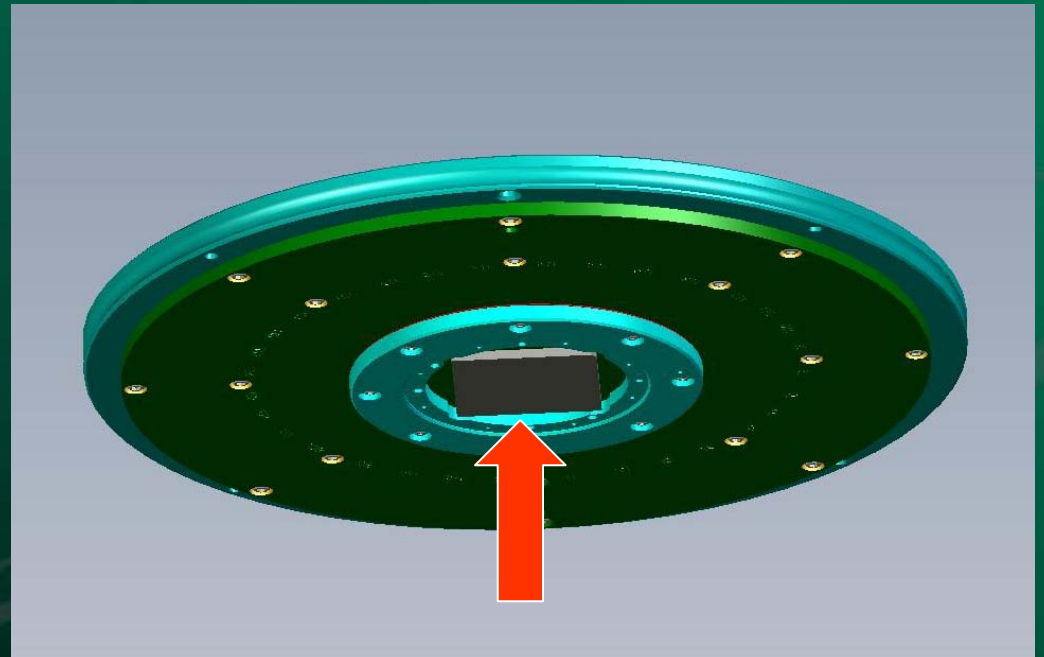
Total = 255Kg

Probe Load on PCB

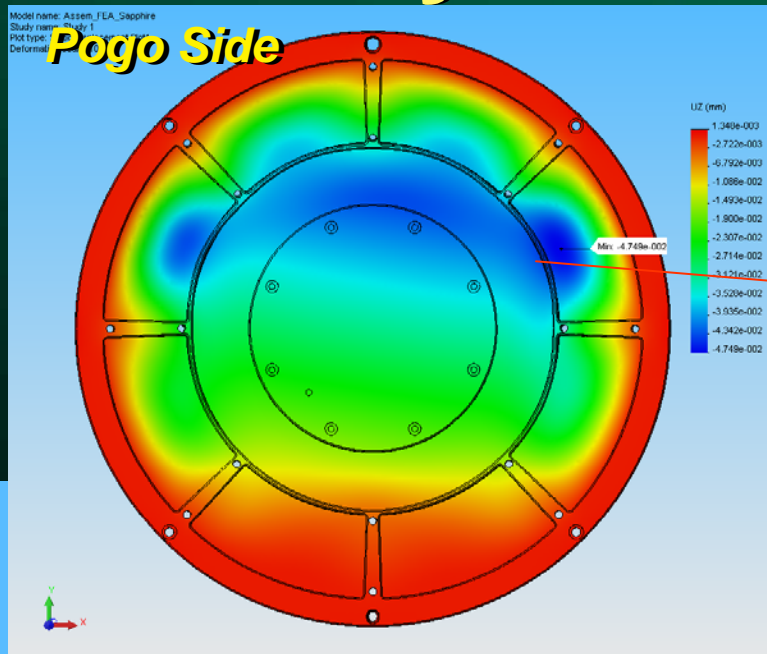
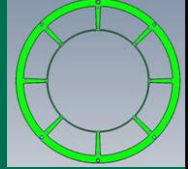


- 8300 Probes
- 3 mils Probes
- 2.5g/mils
- 5 mils Overdrive

Total = 103Kg

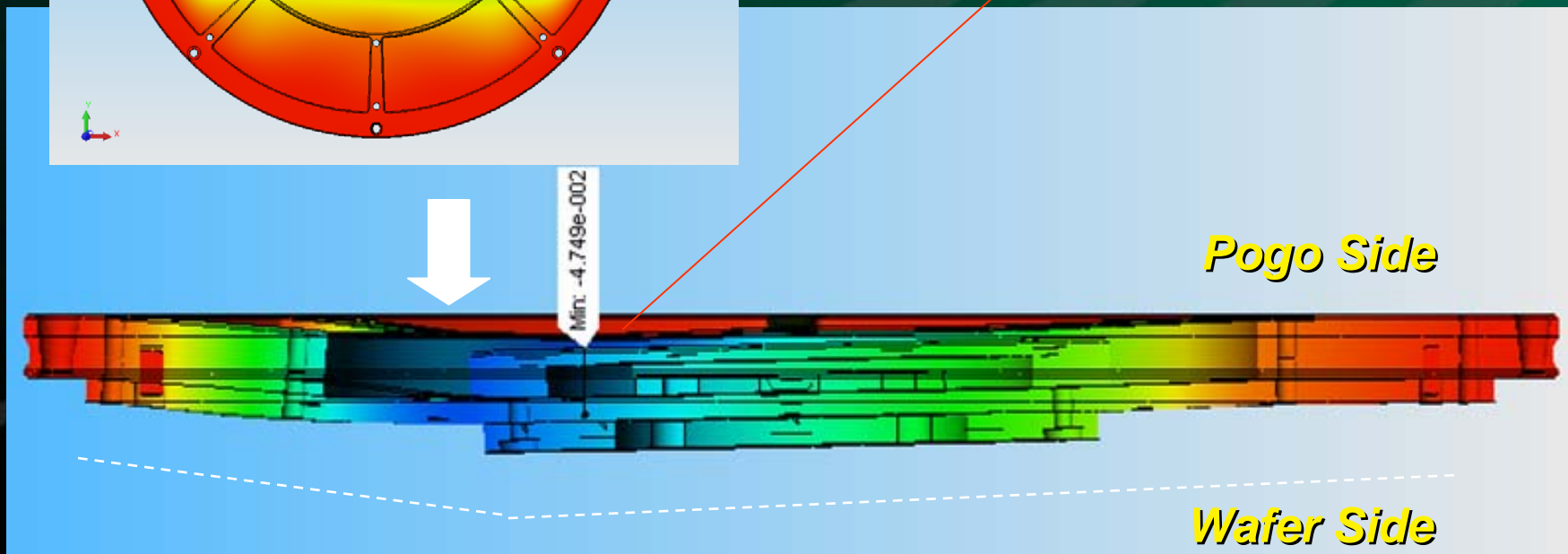


Only with Pogo Force

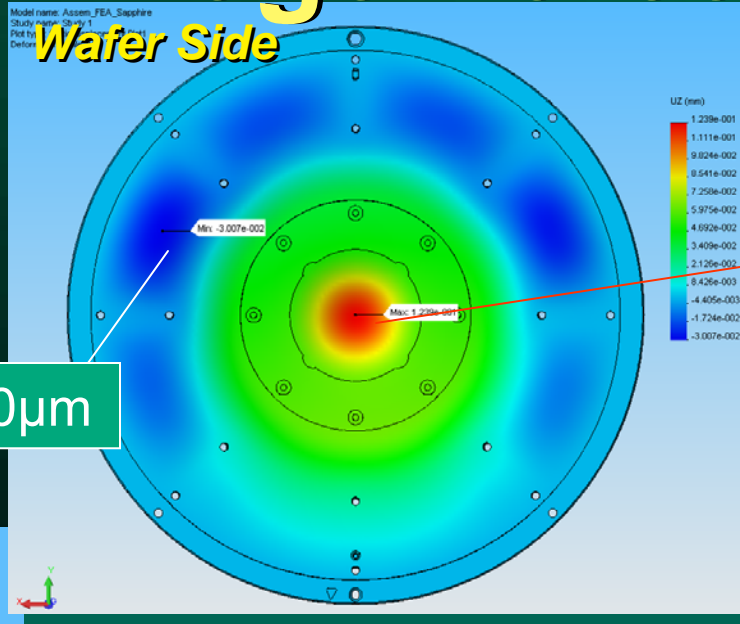
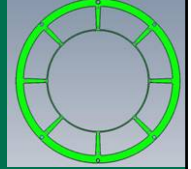


Maximum Displacement
(on Wafer Side Direction):

50 μ m

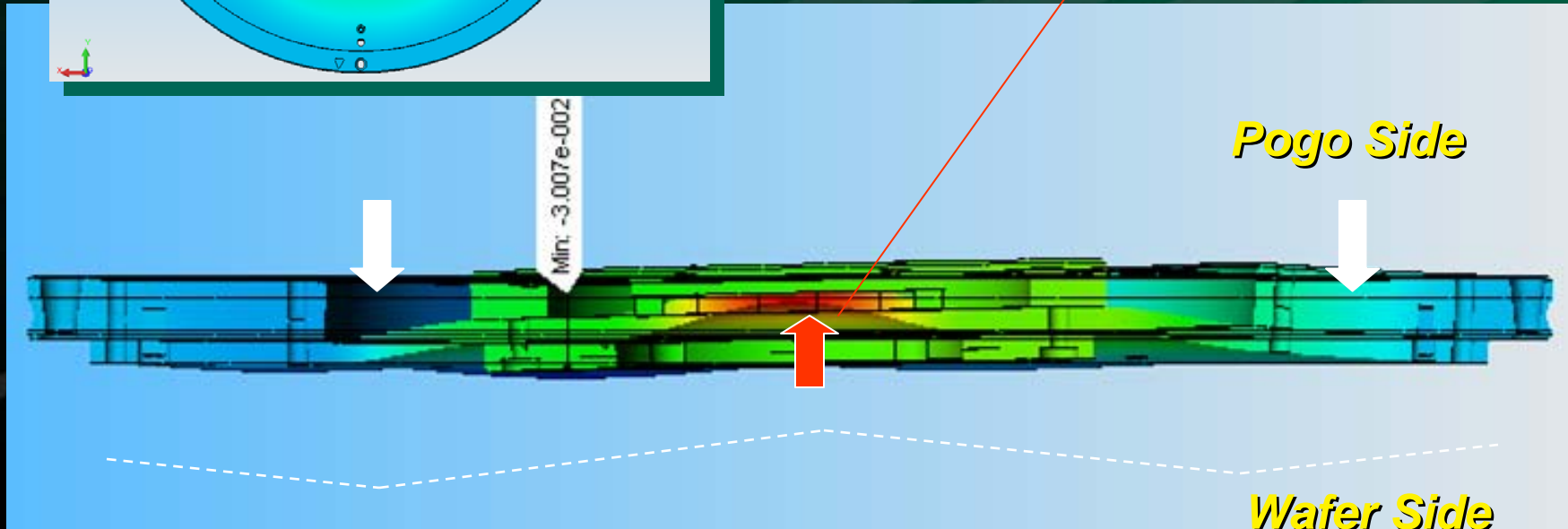


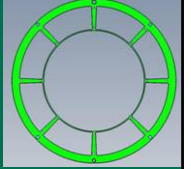
Pogo Force & Probe Load



-30µm

Maximum Displacement
(on tester side direction) :
120µm





Observation

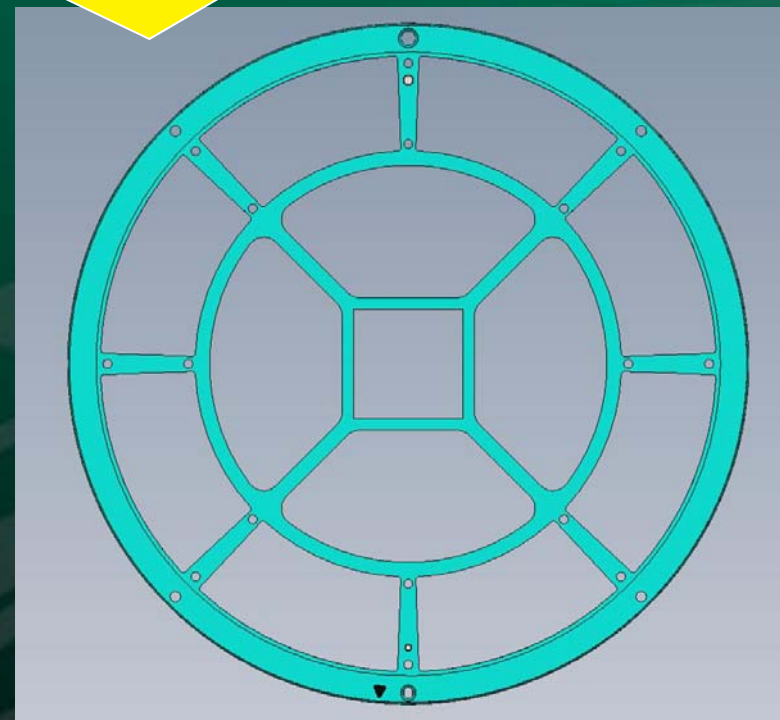
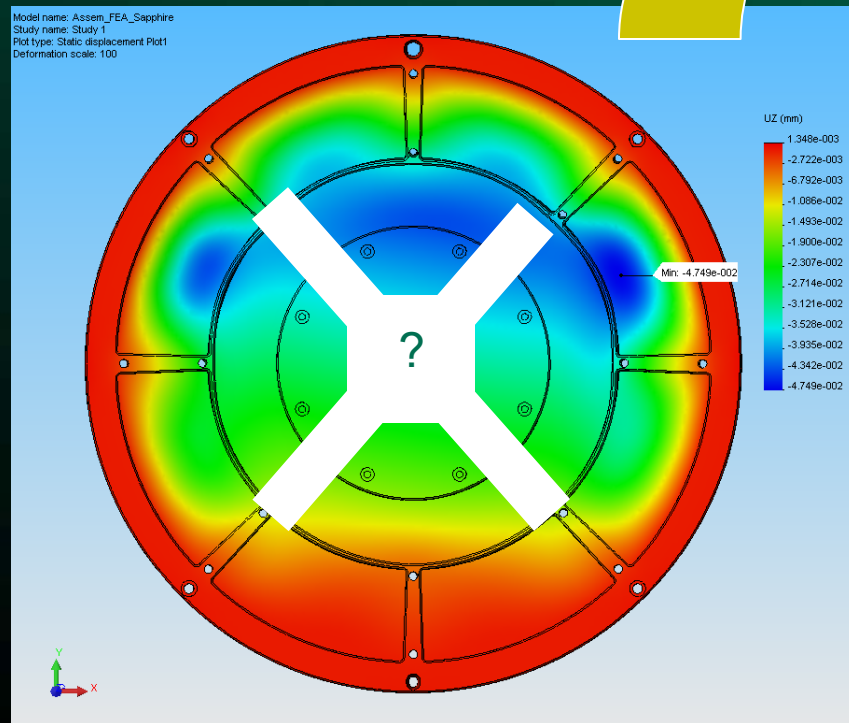
Pogo Force Creates a $50\mu\text{m}$ Deflection of the PCB Top Area:

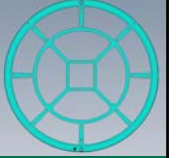
- Unbalanced Pogo Module Force Repartition

Pogo Force with Probe Force Load gives a Deflection of about $120\mu\text{m}$ on the Center PCB Area :

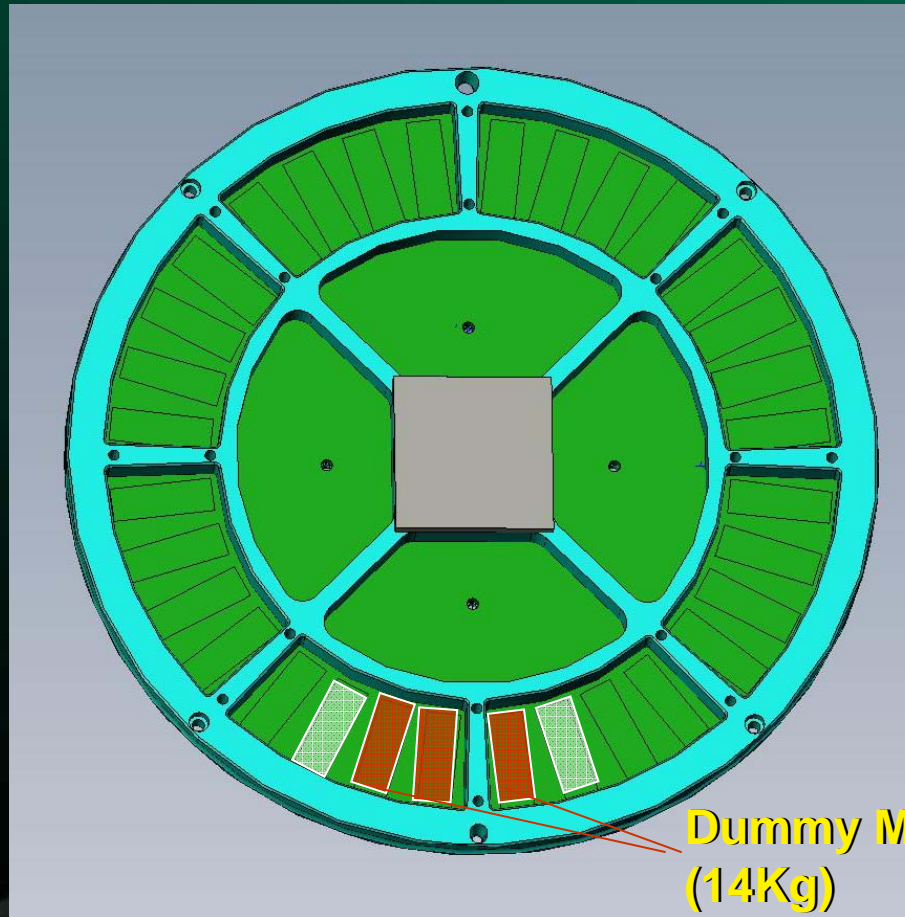
- Inappropriate Standard Stiffener Design

Reduce Deflection - Phase 1



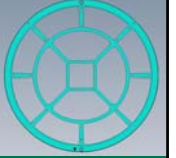


4 Spokes & Dummy Pogo



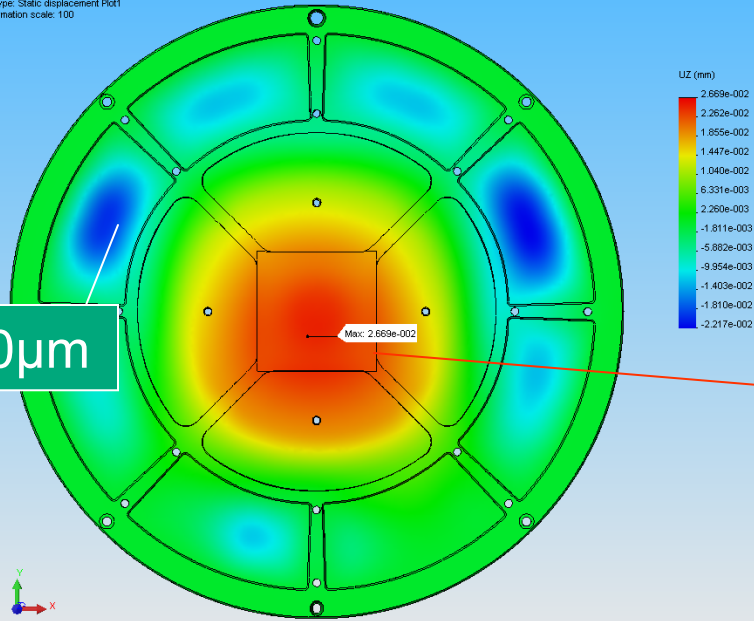
- Stiffener Thickness : 12.7mm
- Spoke Number : 4
- Spoke Width : 6.76mm
- Dummy Pogo Modules added to Balance the Force over the PCB

Total = 296Kg



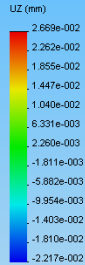
Z Deflection

Model name: Assem_FEA_Sapphire
Study name: Study 2
Plot type: Static displacement Plot1
Deformation scale: 100

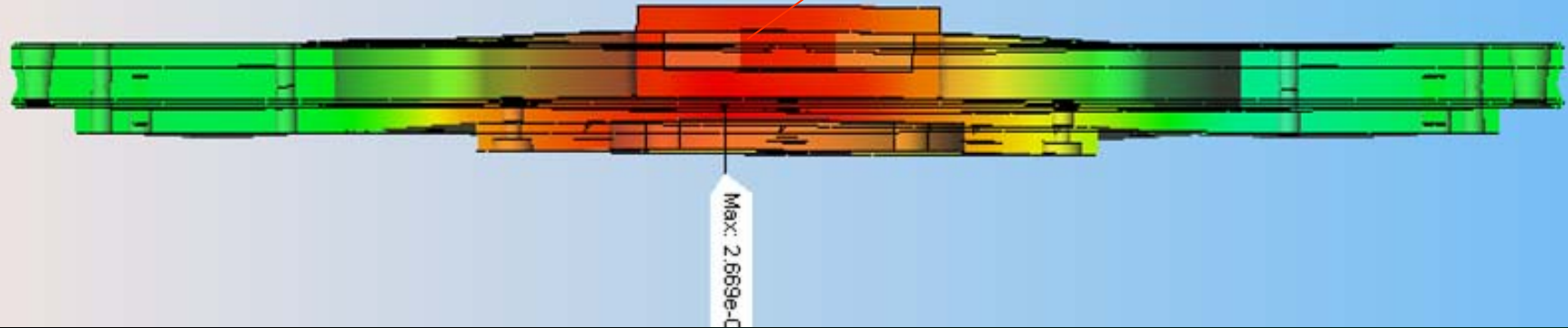


-20µm

Max: 2.669e-002



Maximum Displacement
(on Tester Side Direction) :
25µm



Max: 2.669e-002

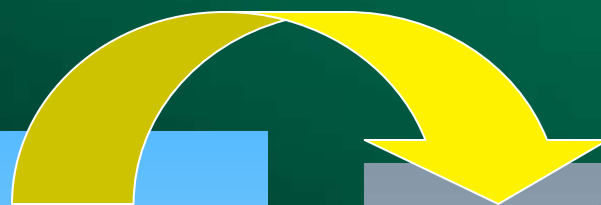
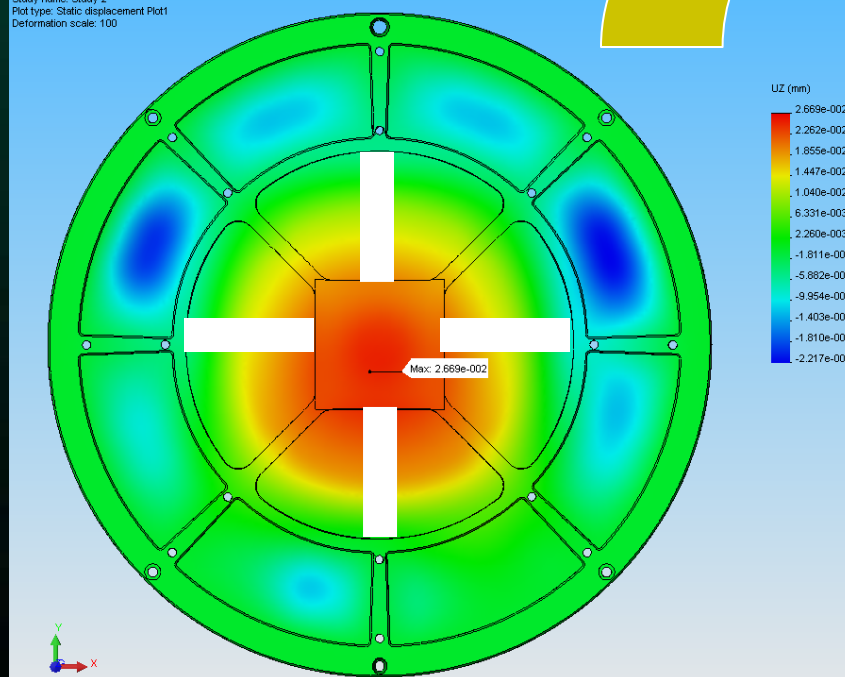


Observation

- 4 Spoke Stiffener Reduced the Maximum Deflection from $120\mu\text{m}$ to $25\mu\text{m}$ (5 times) and Total Deflection is more evenly Spread out
- Dummy Pogo Module can Help to Balance the Deflection over the PCB but has Limitation (add more load and max deflection still not in center of PCB)

Reduce Deflection - Phase 2

Model name: Assem_FEA_Sapphire
Study name: Study 2
Plot type: Static displacement Plot1
Deformation scale: 100



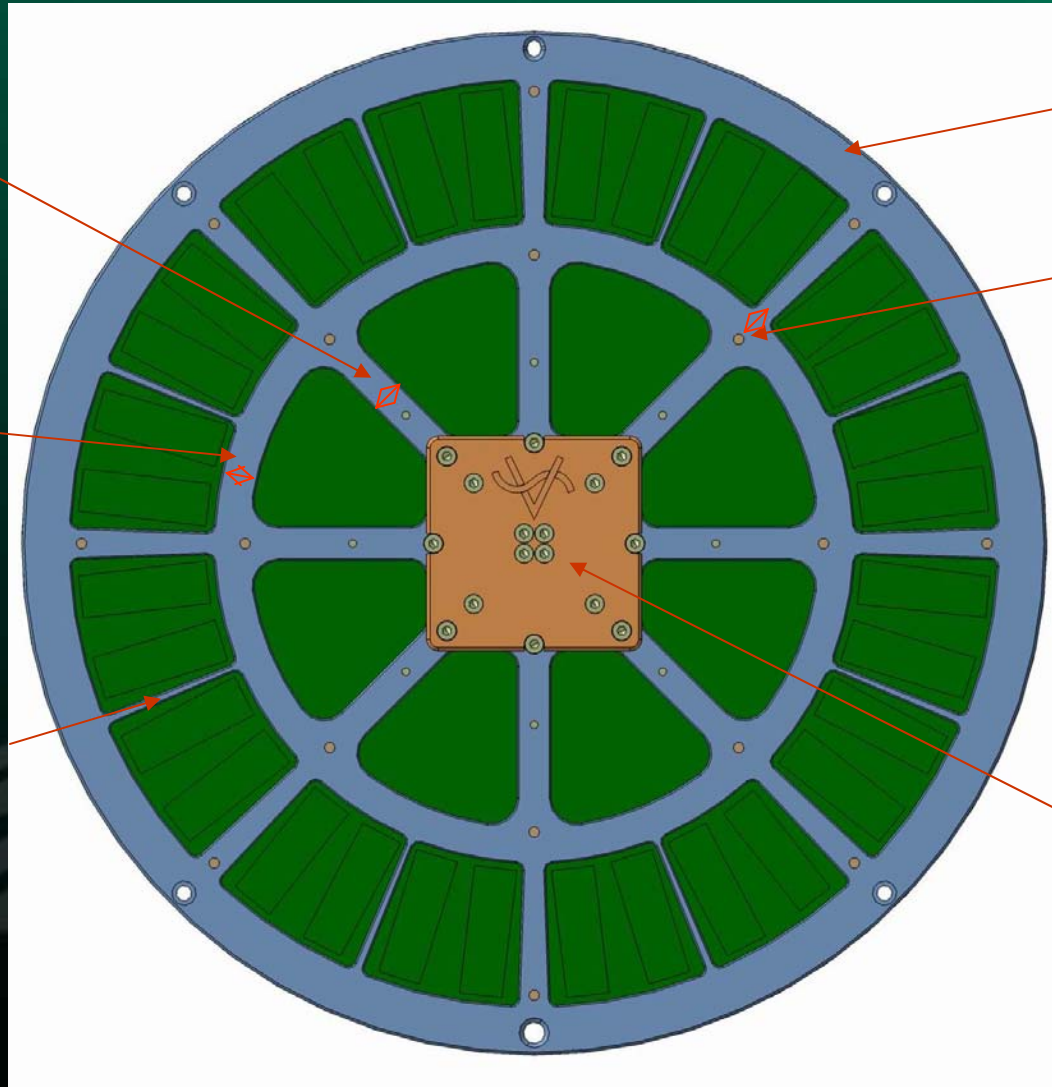


8 Spoke Stiffener

X8 extra Inner Spokes
(10mm Width)

Wider Section

x8 Spokes
between Pogo
Modules



.6inch (15mm)
Thickness

Shift of Screw
Position to a
Wider Spoke
Area

Square Center
with Screws to
Reduce
Deflection
above the MLC

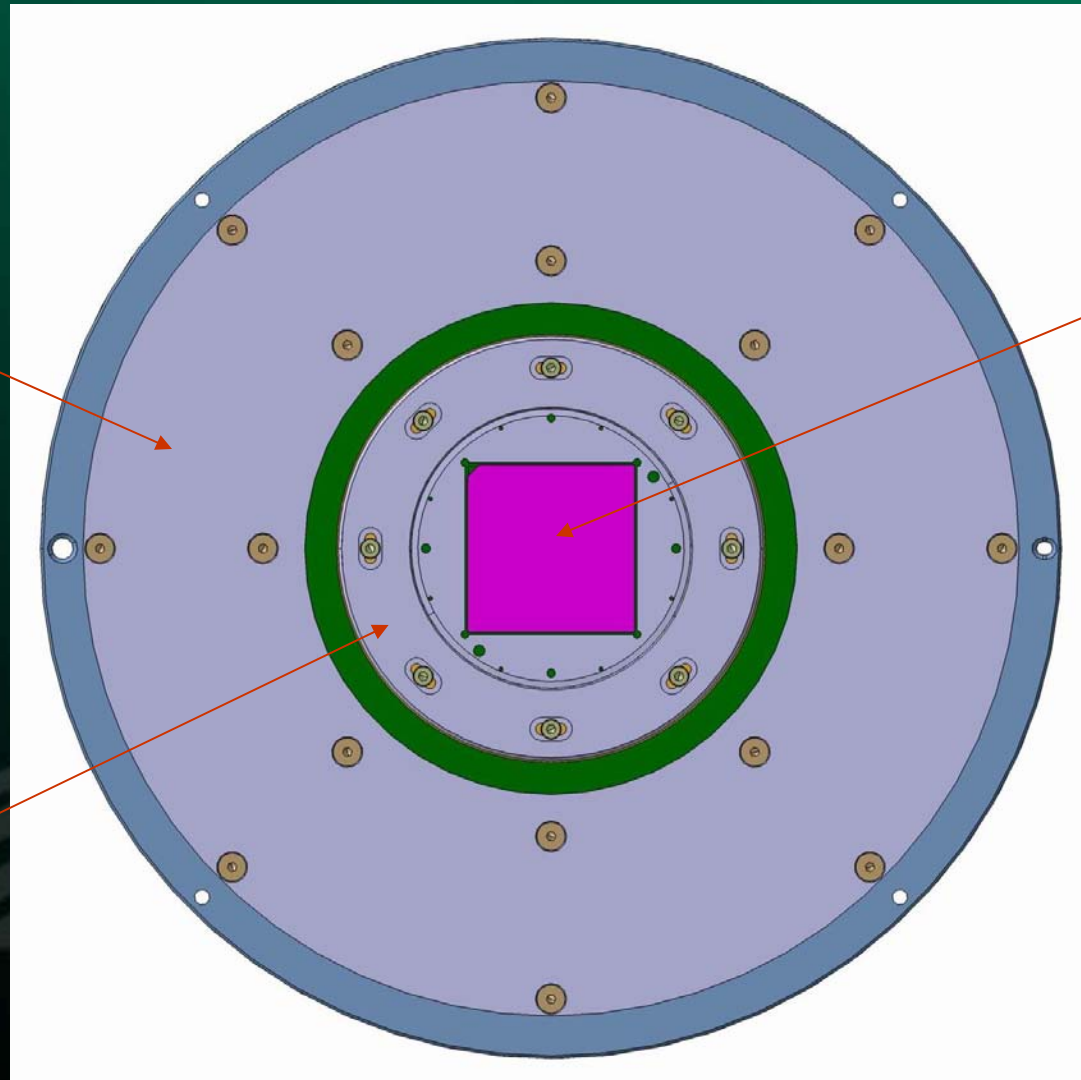


Back Plate Stiffener

Back Plate
Stiffener

MLC

Probe Head
Holder Ring



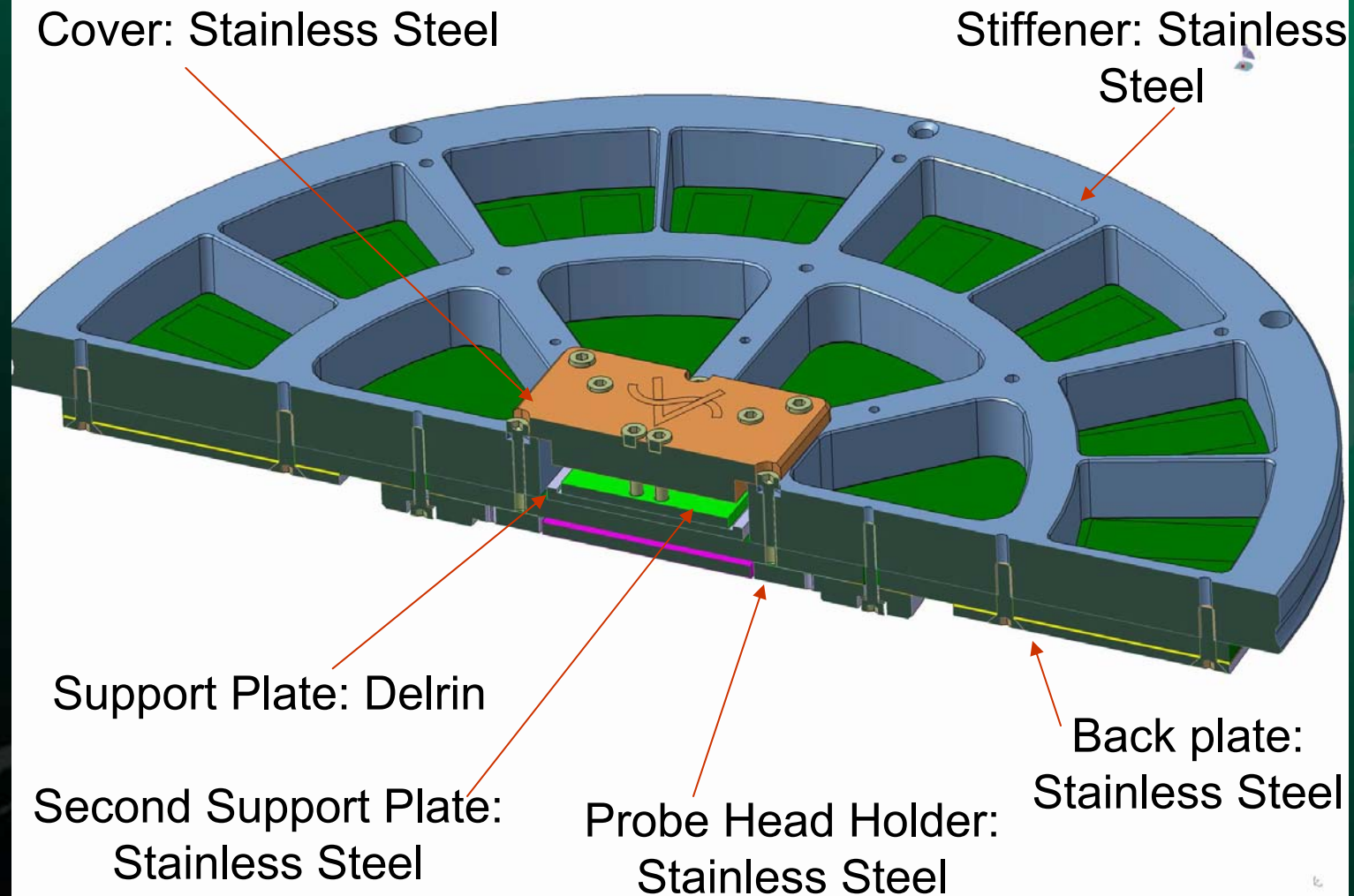
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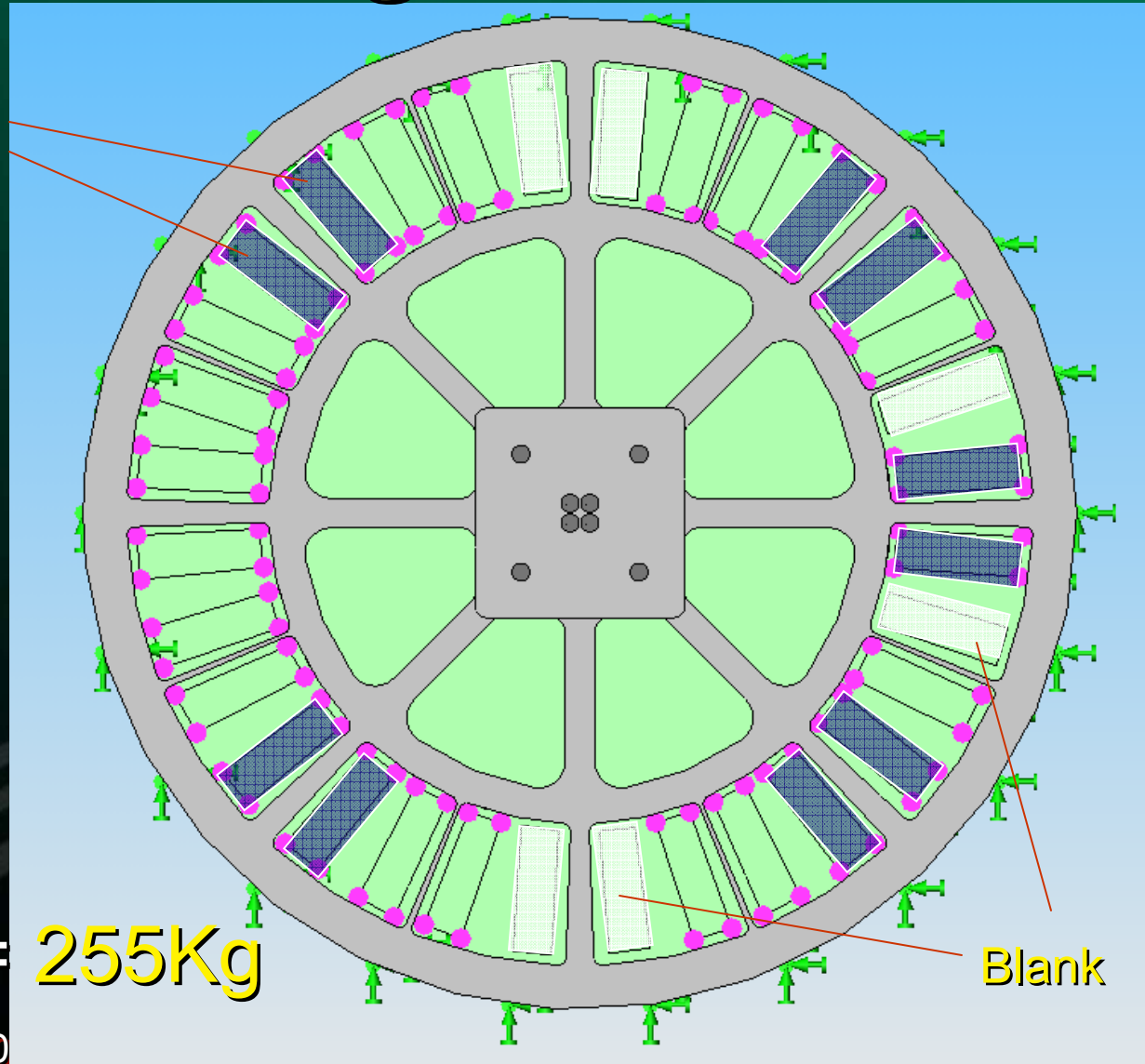
Cross Section





New Pogo Module Load

DPS (14Kg)



Total = 255Kg

Blank

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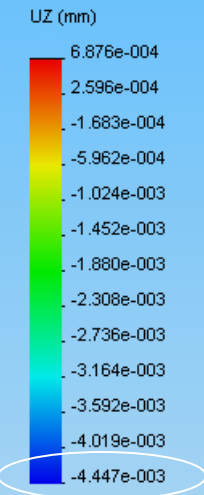
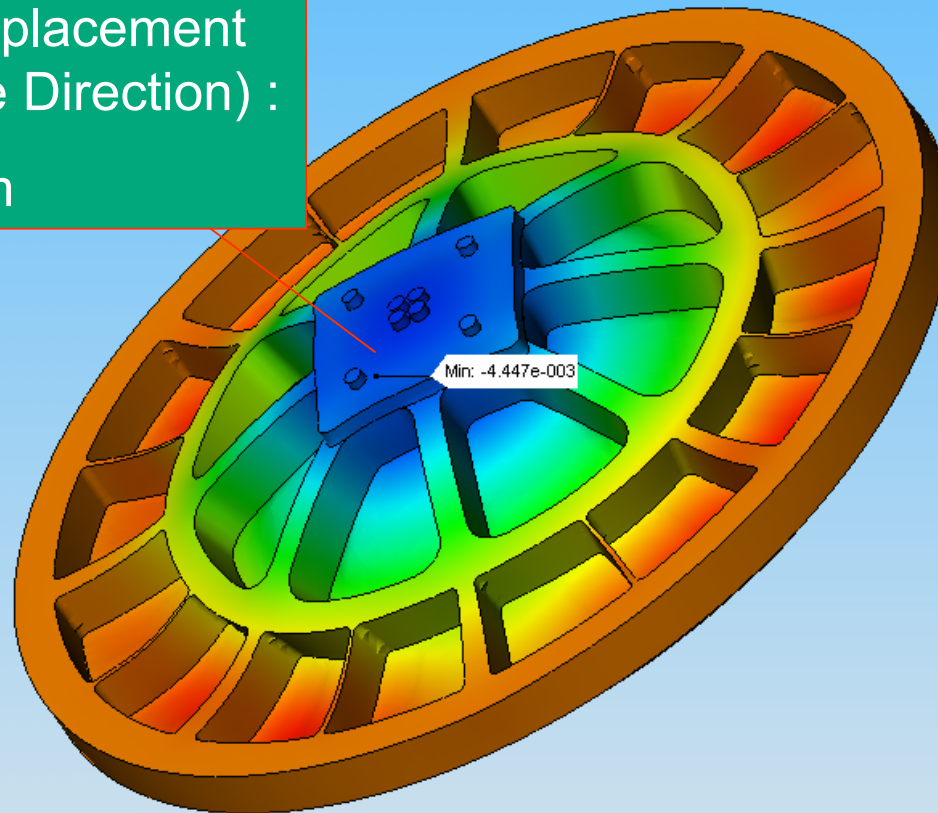


Very Low Deflection

Model name: Assem1
Study name: Study 2
Plot type: Static displacement Plot1
Deformation scale: 6819.21

Deformation Scale: 6819.21

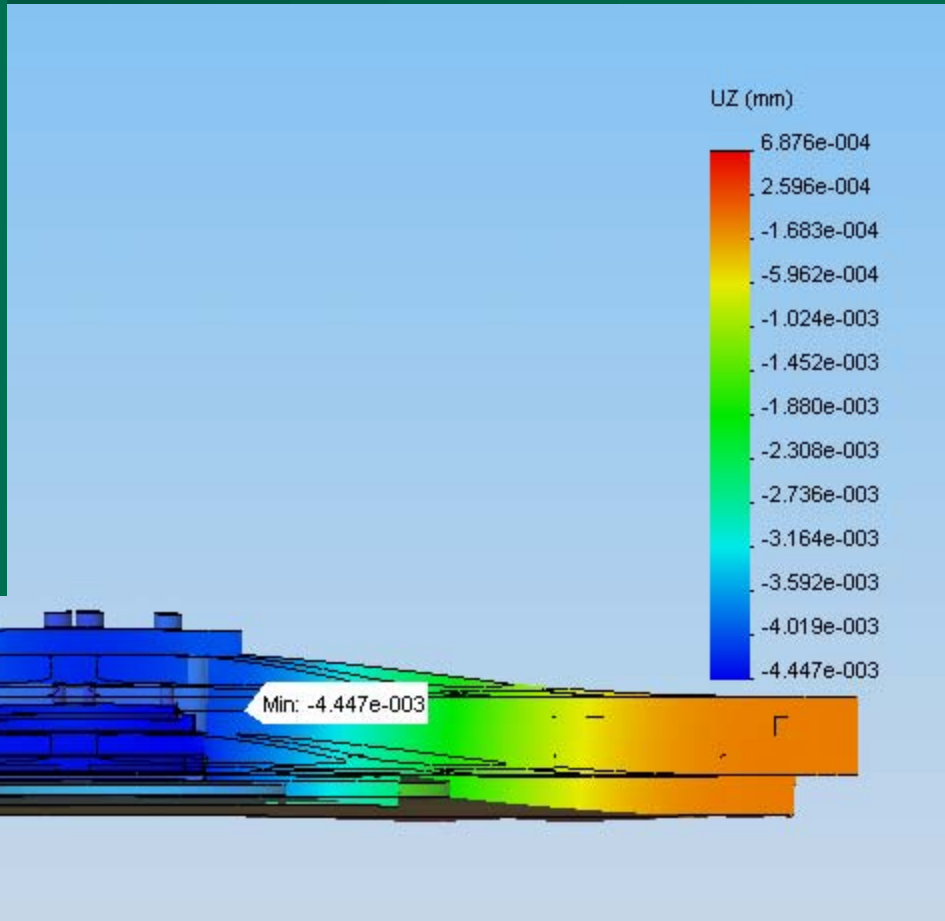
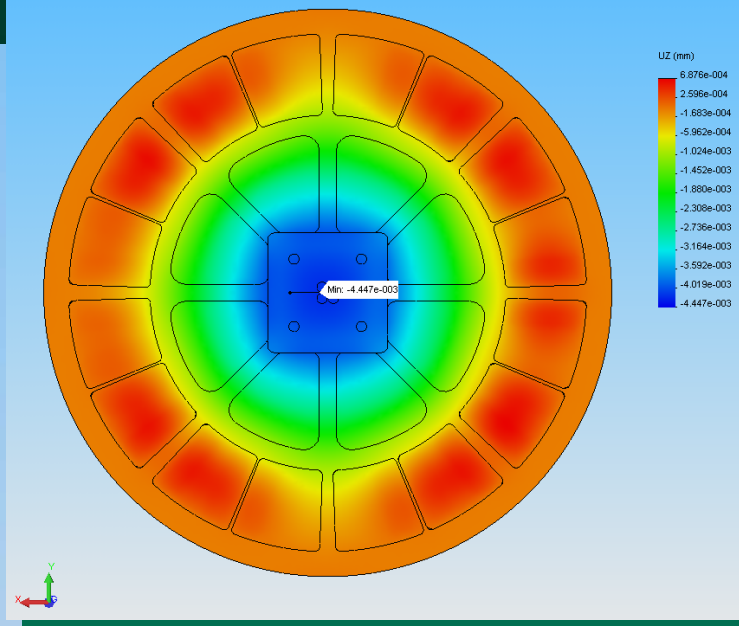
Maximum Displacement
(on Tester Side Direction) :
 $4\mu\text{m}$





Homogenous Deflection

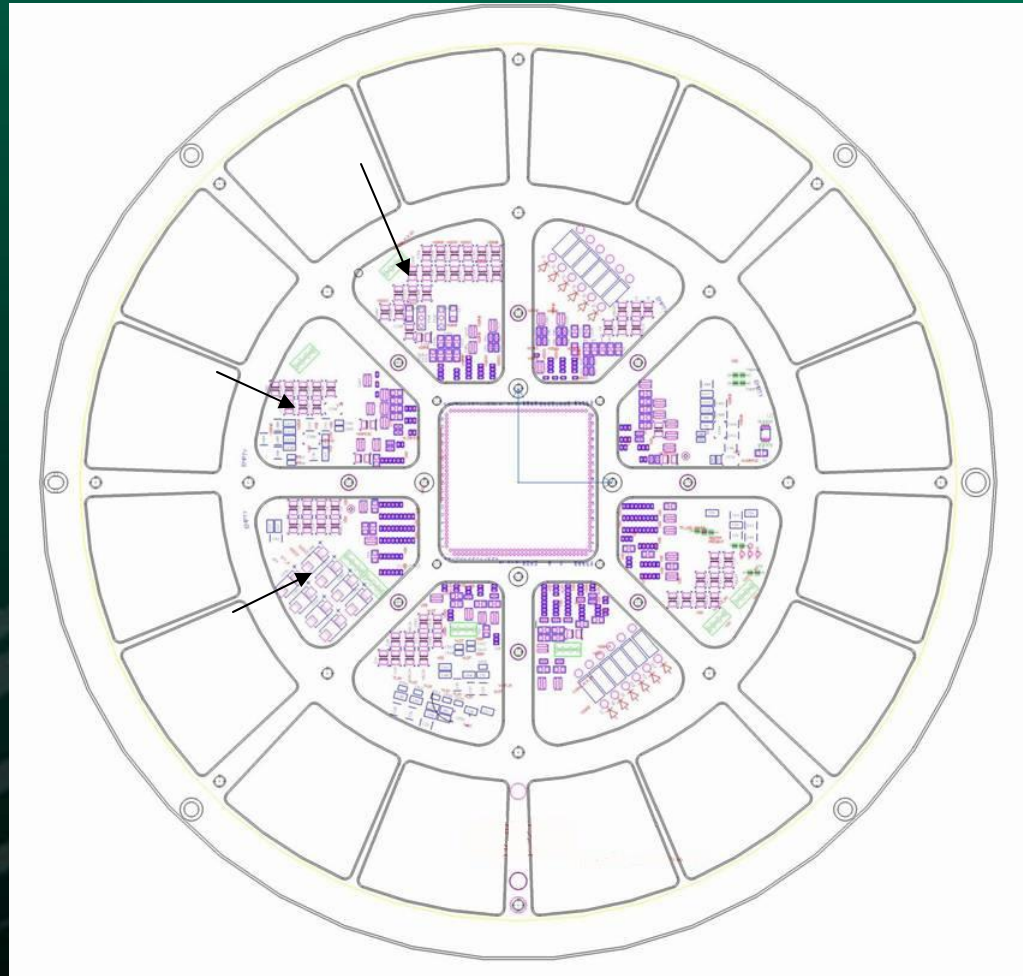
Model name: Assem1
Study name: Study 2
Plot type: Static displacement Plot1
Deformation scale: 0






Last Thing to Check...

✓ Enough Room
for Component
Placement !



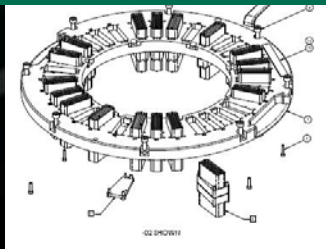
Summary

	Analytical Calculations	Standard Design	<input checked="" type="checkbox"/> 4 Spokes <input checked="" type="checkbox"/> Dummy Module	<input checked="" type="checkbox"/> 8 Spokes <input checked="" type="checkbox"/> Back Plate <input checked="" type="checkbox"/> New Pogo Configuration
Max Deflection	>500 μ m (Only PCB) 90 μ m (4 spokes)	120 μ m	25 μ m	4 μ m
Comments	Only Estimation	High Deflection and Unbalanced Load	x5 time Reduction	x30 time Reduction 

Conclusion

- Use Analytical Solution to Evaluate the Deflection Range. Deflection is Inversely Proportional to Thickness (Power of 3), Spoke Width and Spoke Number.
- FEA to Understand the Root Cause and Reduce Deflection:
 - Define a 3D Model with Appropriated Load and Boundary Condition
 - Find the Critical Areas and Quantify the Max Deflection
 - Optimize the Spoke Parameters and Pogo Population

**Pogo Module
Optimization**



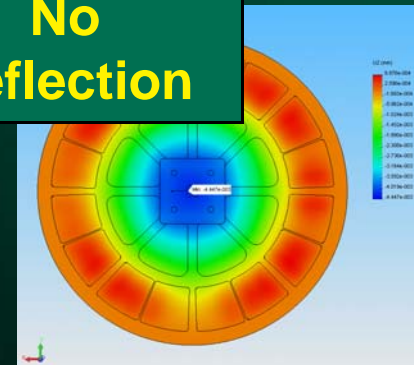
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**Advanced
Stiffener**



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**No
Deflection**



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Thanks for Your Support !

SV Probe Team : JB Hollstein, Isabelle Garidi,
Karen Lynch, Pete Rogan, Bahadir Tunaboynu,
Rehan Kazmi, JM Leger.

QUESTIONS ?